

**AMENDMENTS TO THE CLAIMS:**

Kindly replace the previous claim set with the claim set that appears below in which Claims 19 and 21-23 have been cancelled and Claim 1 has been amended to read as follows:

1. (Currently Amended) A photocurable encapsulant composition comprising:

(i) a uv curable component;

(ii) a component for initiating cure of the uv curable component present in an amount within the range of about 0.1 to about 2 percent by weight of the total composition;

(iii) an opacifying component comprising a lactone in which an aromatic ring is fused to the lactone ring, which opacifying component has a first colour which is sufficiently transparent to uv light so as to substantially unaffected cure of the uv curable component and which is activatable to change colour to a second colour which is sufficiently opaque to render the cured product of the composition substantially opaque to visible light; and

(iv) an adhesion-promoting component, wherein the composition, when applied on a part as an encapsulant composition, achieves ~~sufficient~~ a cure through volume of at least 600-800 um after exposure to uv light to allow a sufficient thickness of the encapsulant composition to

cure on the part so that the encapsulant composition is opaque and the part is not visible through the encapsulant composition.

2. (Original) A composition according to Claim 1, wherein the composition is capable of curing through a volume of at least about 1 mm.

3. (Previously Presented) A composition according to Claim 1, wherein the composition is capable of curing radiation at a wavelength of at least 290 nm.

4. (Previously Presented) A composition according to Claim 1 further comprising an inorganic filler component.

5. (Previously Presented) A composition according to Claim 1, wherein the composition is capable of curing in a time of less than about 15 seconds.

6. (Previously Presented) A composition according to Claim 1 wherein the uv curable component comprises an epoxy resin material.

7. (Previously Presented) A composition according to Claim 6, wherein the epoxy resin component is a member selected from the group consisting of cycloaliphatic epoxy resins; polyphenol glycidyl ethers; polyglycidyl ethers of pyrocatechol, resorcinol, hydroquinone, 4,4'-dihydroxydiphenyl methane, 4,4'-dihydroxy-3,3'-dimethyldiphenyl methane, 4,4'-dihydroxydiphenyl dimethyl methane, 4,4'-dihydroxydiphenyl methyl methane, 4,4'-dihydroxydiphenyl cyclohexane, 4,4'-dihydroxy-3,3'-dimethyldiphenyl propane, 4,4'-dihydroxydiphenyl sulfone, and tris(4-hydroxyphenyl)methane; polyglycidyl ethers of the chlorination and bromination products of the above-mentioned diphenols; polyglycidyl ethers of novolacs; polyglycidyl ethers of diphenols obtained by esterifying ethers of diphenols obtained by esterifying salts of an aromatic hydrocarboxylic acid with a dihaloalkane or dihalogen dialkyl ether; polyglycidyl ethers of polyphenols obtained by condensing phenols and long-chain halogen paraffins containing at least two halogen atoms; phenol novolac epoxy resins; cresol novolac epoxy resins; and combinations thereof.

8. (Previously Presented) A composition according to Claim 6 wherein the epoxy resin component is a cycloaliphatic

epoxy resin, bisphenol A epoxy resin, bisphenol F epoxy resin and combinations thereof.

9. (Previously Presented) A composition according to any one of Claim 6, wherein the epoxy resin component is used in an amount of up to about 98 percent by weight of the total composition.

10. (Previously Presented) A composition according to Claim 1 wherein the opacifying component comprises a lactone in which an aromatic ring is fused to the lactone ring.

11. (Previously Presented) A composition according to Claim 1 wherein the component for initiating cure of the curable component also participates in the colour change of the opacifying component.

12. (Previously Presented) A composition according to Claim 1 wherein the component for initiating cure of the curable component is an onium salt.

13. (Previously Presented) A composition according to Claim 1 wherein the adhesion promoting component comprises silane.

14. (Original) A composition according to Claim 13 wherein the silane is selected from the group consisting of: cycloaliphatic silanes, epoxy silanes, and amino silanes and combinations thereof.

15. (Previously Presented) A composition according to Claim 1 wherein the composition further comprises a photosensitiser component.

16. (Original) A composition according to Claim 15, wherein the photosensitiser component is selected from the group consisting of thioxanthenes, anthracene, perylene, phenothazine, 1,2 benzanthracene, coronene, pyrene, tetracene and combinations thereof.

17. (Previously Presented) A composition according to Claim 15, wherein the photosensitiser is a thioxanthone.

18. (Previously Presented) A composition according to Claim 15, wherein the photosensitiser is used in an amount within the range of about 0.01 to 1 percent by weight of the total composition.

Claim 19. (Cancelled)

20. (Previously Presented) A composition according to Claim 1, further comprising a dye or pigment.

Claims 21-24. (Cancelled)

25. (Withdrawn) A method of applying a composition according to Claim 1 as an encapsulant for encapsulating electronic components comprising the steps of:

(i) applying the composition onto a part as an encapsulant;  
and

(ii) exposing the composition to uv light so as to achieve sufficient cure through volume on exposure to the uv light to allow a sufficient thickness of the encapsulant composition to cure on the part so that the encapsulant composition is opaque and the part is not visible through the encapsulant composition.